



## Overmold Assembly Build Sheet

Original request  
 Changed request Rev # \_\_\_\_\_

QP Internal S.O. #: \_\_\_\_\_

QP Quote #: \_\_\_\_\_

QP Sales Contact: \_\_\_\_\_

### CUSTOMER CONTACT INFORMATION

Company: \_\_\_\_\_ Contact Name: \_\_\_\_\_ Date: \_\_\_\_\_

Phone: \_\_\_\_\_ Email: \_\_\_\_\_

P.O. #: \_\_\_\_\_

Is this item under the jurisdiction of the International Traffic in Arms Regulations (ITAR)? Yes No

### DELIVERY REQUEST

LEAD TIMES WILL VARY BASED ON SCOPE OF WORK AND QUANTITY.

STANDARD LEAD TIME FOR BENCHMARK ORDER (PKG: QFN, PKG QTY: <200, WIRE COUNT: <50, SINGLE DIE ATTACH) IS 5 DAYS. EXPEDITE (4 DAYS). PREMIUM (3 DAYS).

Standard Expedite Premium

### DIE INFORMATION:

ALL WAFER PROCESSING REQUIRES A BACKGRIND/DICING BUILD SHEET TO BE COMPLETED AND ATTACHED SEPARATELY.

Die Format: Waffle Pack Gel-Pak Diced Wafer on Tape Wafer (requires processing) Other: \_\_\_\_\_

Die Size: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils (a) Wafer ID/Die ID: (b) Lot # (c) Qty of Devices to be Assembled from ID

Pad Pitch: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils Bond 1a. \_\_\_\_\_ 1b. \_\_\_\_\_ 1c. \_\_\_\_\_

Pad Dims: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils Bond 2a. \_\_\_\_\_ 2b. \_\_\_\_\_ 2c. \_\_\_\_\_

Pad Opening: \_\_\_\_\_ X \_\_\_\_\_  $\mu$ m or mils 3a. \_\_\_\_\_ 3b. \_\_\_\_\_ 3c. \_\_\_\_\_

Thickness: \_\_\_\_\_  $\mu$ m or mils 4a. \_\_\_\_\_ 4b. \_\_\_\_\_ 4c. \_\_\_\_\_

Metalization: Aluminum Gold Other (Specify): \_\_\_\_\_ Probed? Yes No Passivated? Yes No

### DEVICE INFORMATION

Device Name: \_\_\_\_\_ Pin Count: \_\_\_\_\_ Lead Pitch: \_\_\_\_\_ Die Per Package: \_\_\_\_\_ Wire Count Per Package: \_\_\_\_\_

Qty of Devices to be Assembled: \_\_\_\_\_ Body Size (mm): \_\_\_\_\_ X \_\_\_\_\_

Packages provided by: Customer Quik-Pak

Package Type: QFN QP Package Part #: \_\_\_\_\_

Package Description: \_\_\_\_\_

Package Thickness (mm) .45 .70 .90 1.37 1.45 2.00

### SPECIAL INSTRUCTIONS (Attach additional documents if needed)

### CUSTOMER FURNISHED MATERIALS:

PLEASE LIST ANY ADDITIONAL CFMs THAT WILL BE SHIPPED TO QUIK-PAK. IF MORE SPACE IS NEEDED, PLEASE ATTACH ADDITIONAL DOCUMENTS.

1. \_\_\_\_\_ 2. \_\_\_\_\_ 3. \_\_\_\_\_

4. \_\_\_\_\_ 5. \_\_\_\_\_ 6. \_\_\_\_\_

7. \_\_\_\_\_ 8. \_\_\_\_\_ 9. \_\_\_\_\_

## ASSEMBLY FLOW

ALL WIRE BONDING REQUIRES A BONDING DIAGRAM BE ATTACHED WITH CLEARLY LABELED PIN 1, DIE ORIENTATION, AND WIRE BONDS.

Please indicate file format: CAD Drawing Other (.jpg, .pdf, Powerpoint) etc.

SelectDieFrom: Center of Wafer(s) Wafer Map(s)

Die Attach Material (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT MATERIALS):

\_\_\_\_ Conductive Epoxy      \_\_\_\_ Thermally Conductive/Electrically Non-Conductive  
\_\_\_\_ Non-Conductive Epoxy      \_\_\_\_ High Thermally Conductive/Electrically Conductive

Gold Wire Diameter (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT WIRE DIAMETER):

\*STANDARD MATERIAL, OTHER OPTIONS MAY INCREASE COST/LEADTIME

\_\_\_\_ 0.7 mil    \_\_\_\_ 0.8 mil    \_\_\_\_ 1.0 mil    \_\_\_\_ 1.2 mil  
\_\_\_\_ 1.3 mil    \_\_\_\_ 1.5 mil    \_\_\_\_ 2.0 mil    \_\_\_\_ Other (Al and Cu available - call for wire size)

Heavy Wire: \_\_\_\_ 5 mil    \_\_\_\_ 10 mil    \_\_\_\_ 15 mil    \_\_\_\_ 20 mil

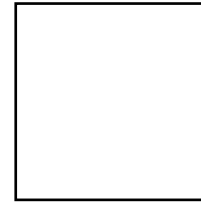
Gold Ribbon: \_\_\_\_ 1 X 2    \_\_\_\_ 1 X 3    \_\_\_\_ 1 X 4

Marking (MAX CHARACTER LENGTH AND NUMBER OF ROWS WILL VARY BASED ON PACKAGE SIZE. CONTACT QP FOR DESIGN APPROVAL AND COST):

Mark pin 1 on device?

No Custom Marking  
Pad Print (White on Black) - Email artwork in native .EPS or .AI file format  
Laser Mark (Black on Black) - Email artwork in native .EPS or .AI file format  
Hand Mark (Max 1-3 characters):

Serialization (MAY INCREASE MARKING COSTS/LEADTIME). Please describe:



Mark pin 1 corner  
and indicate how  
marking should  
appear on package  
relative to pin 1.

## SHIPPING (Contact QP with any special requests)

Reject Parts Disposition: Return to Customer Bag and Tag Destroy

\*Unless otherwise noted all extra materials will be returned.

Shipping Method (Please Select)

Account #: \_\_\_\_\_

Pickup FedEx DHL UPS Courier Special Instructions

Ship To Address (Finished Product):

Attn: \_\_\_\_\_

Address: \_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

Ship To Address (Excess Die and Materials):

Attn: \_\_\_\_\_

Address: \_\_\_\_\_  
\_\_\_\_\_  
\_\_\_\_\_

Include Certificate of Conformance

Ship Materials In

Trays

Tubes

Other: \_\_\_\_\_

Containers Provided by:

Quik-Pak

Customer

## For Quik-Pak Internal Use Only:

Orders meeting one of the following requirements require signatures by representatives in the following departments:

☐ Over \$20k production ☐ ISO-13485 Processing ☐ Change in instructions after order has been released to

Sales: \_\_\_\_\_ Date: \_\_\_\_\_

Engineering: \_\_\_\_\_ Date: \_\_\_\_\_

Manufacturing: \_\_\_\_\_ Date: \_\_\_\_\_

QA: \_\_\_\_\_ Date: \_\_\_\_\_

Per Quik-Pak quality program, risk assessment is required on orders over \$100k and/or Medical orders built under ISO-13485 std.